

IN THE SPECIFICATION

Please replace the title with the following:

**~~“LAYERED CIRCUIT BOARDS, METHODS OF PRODUCTION AND USES
THEREOF~~ A METHOD OF PRODUCING AN ELECTRONIC COMPONENT”**

Please amend the abstract to the following:

~~Compositions and methods are provided whereby printed wiring boards may be produced that comprise a) a substrate layer, and b) a solid, substantially planar optical wave guide laminated onto the substrate layer. The printed wiring board further comprises at least one of a laminating material or a cladding material coupled to the wave guide, and at least one additional layer coupled to the laminating material or the cladding material. Methods are also~~ A method for making an electronic component is provided whereby an electronic component is produced that comprises a) providing a substrate layer; b) providing a solid, substantially planar optical wave-guide; and c) laminating the solid, substantially planar optical wave-guide onto the substrate layer.